1.50mm Height Top View Super Yellow Chip LEDs Technical Data Sheet

Part No.: DL-TOP5050UYC-4UY

Features:

- 1. P-LCC-6 package.
- 2. White package.
- 3. Optical indicator.
- 4. Colorless clear window.
- 5. Ideal for backlight and light pipe application.
- 6. Inter reflector.
- 7. Wide viewing angle.
- 8. Suitable for vapor-phase reflow, infrared reflow and wave solder processes.
- 9. Suitable for all SMT assembly and solder process.
- 10. Computable with automatic placement equipment.
- 11. Available on tape and reel (12mm Tape).
- 12. The product itself will remain within RoHS compliant Version.

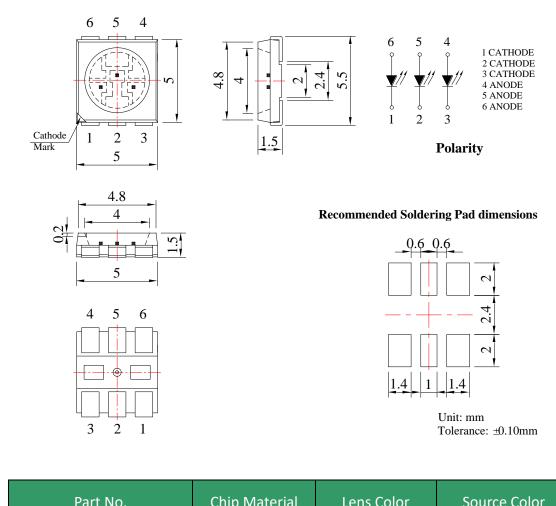
Descriptions:

 The TOP5050 is available in soft red, orange, yellow, green, blue and white. Due to the Package design, the LED has wide viewing angle and optimized light coupling by inter reflector, this feature makes the SMT TOP LED ideal for light pipe Application. The low current requirement makes this device ideal for portable equipment or any other application where power is at a premium.

Applications:

- 1. Automotive: Backlight in dashboards and switches.
- 2. Telecommunication: Indicator and backlight in telephone and fax.
- 3. Indicator and backlight for audio and video equipment.
- 4. Indicator and backlight in office and family equipment.
- 5. Flat backlight for LCD's, switches and symbols.
- 6. Light pipe application.
- 7. General use.

Double Light Package Dimension:



Part No.	Chip Material	Lens Color	Source Color
DL-TOP5050UYC-4UY	AlGaInP	Water Clear	Super Yellow

Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ± 0.25mm (.010") unless otherwise specified.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings at Ta=25 °C				
Parameters	Symbol	Max.	Unit	
Power Dissipation (Per Chip)	PD	95	mW	
Peak Forward Current (Per Chip) (1/10 Duty Cycle, 0.1ms Pulse Width)	IFP	100	mA	
Continuous Forward Current (Per Chip)	IF	25	mA	
Reverse Voltage (Per Chip)	VR	5	V	
Electrostatic Discharge (HBM)	ESD	2000	V	
Operating Temperature Range	Topr	-40 ℃	to +80℃	
Storage Temperature Range	Tstg	-40℃ to +85℃		
Soldering Temperature	Tsld	260℃ for 5 Seconds		

Electrical Optical Characteristics at Ta=25 $^\circ C$

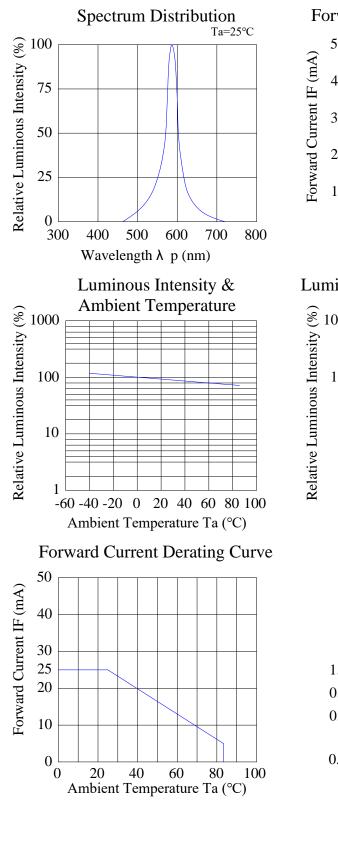
Parameters	Symbol	Min.	Тур.	Max.	Unit	Test Condition
Luminous Intensity	IV	2500	3000		mcd	IF=20mA (Note 1) (Per Chip)
Viewing Angle	20 _{1/2}		120		Deg	IF=20mA (Note 2) (Per Chip)
Peak Emission Wavelength	λр		588		nm	IF=20mA (Per Chip)
Dominant Wavelength	λd		592		nm	IF=20mA (Note 3) (Per Chip)
Spectral Line Half-Width	Δλ		10		nm	IF=20mA (Per Chip)
Forward Voltage	VF	1.80	2.20	2.80	V	IF=20mA (Per Chip)
Reverse Current	IR			10	μA	V _R =5V (Per Chip)

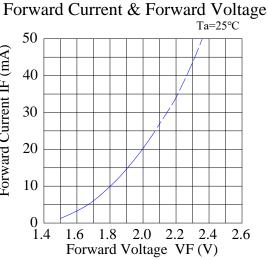
Notes:

- 1. Luminous Intensity Measurement allowance is ± 10%.
- 2. $\theta_{1/2}$ is the off-axis angle at which the luminous intensity is half the axial luminous intensity.
- The dominant wavelength (λd) is derived from the CIE chromaticity diagram and represents the single wavelength which defines the color of the device.

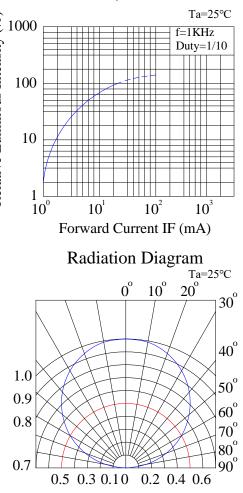
Typical Electrical / Optical Characteristics Curves (Per Chip)

(25 $^\circ\!\mathrm{C}$ Ambient Temperature Unless Otherwise Noted)





Luminous Intensity & Forward Current



Reliability Test Items And Conditions (Per Chip):

The reliability of products shall be satisfied with items listed below:

Confidence level: 90%.

LTPD: 10%.

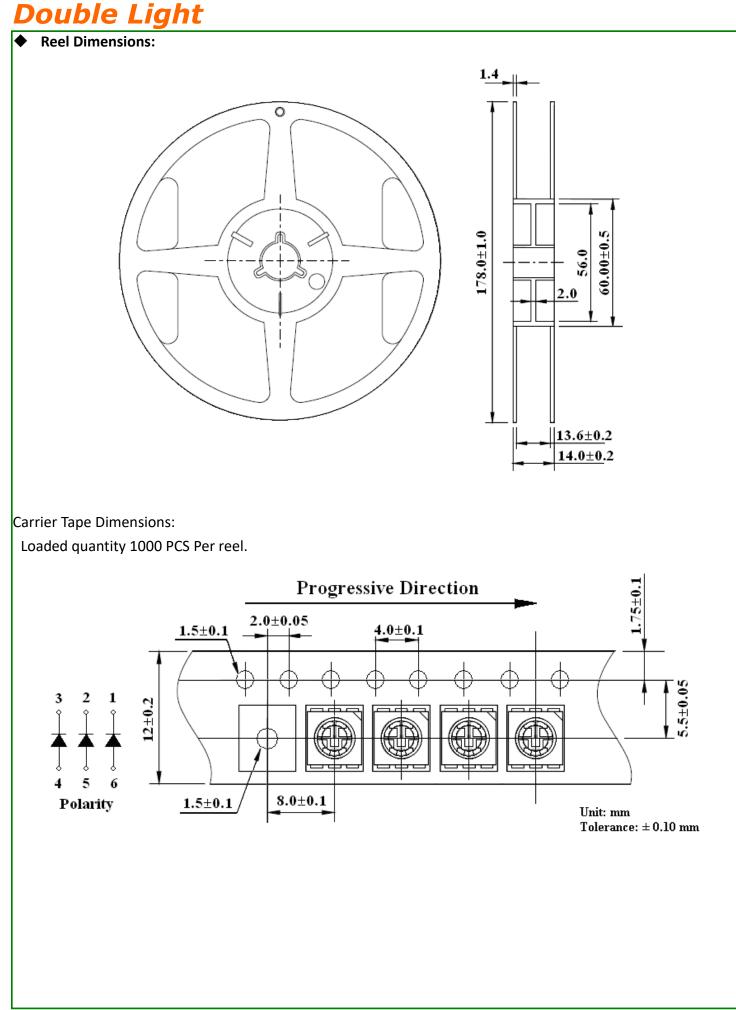
1) Test Items and Results:

No.	Test Item	Test Hours/Cycles	Test Conditions	Sample Size	Ac/Re
1	Resistance to Soldering Heat	6 Min	Tsld=260±5℃, Min. 5sec	25pcs	0/1
2	Thermal Shock	300 Cycles	H: +100°C 5min ∫ 10 sec L: -10°C 5min	25pcs	0/1
3	Temperature Cycle	300 Cycles	H: +100°℃ 15min ∫ 5min L: -40°℃ 15min	25pcs	0/1
4	High Temperature Storage	1000Hrs.	Temp: 100 ℃	25pcs	0/1
5	DC Operating Life	1000Hrs.	IF=20mA	25pcs	0/1
6	Low Temperature Storage	1000Hrs.	Temp: −40 °C	25pcs	0/1
7	High Temperature/ High Humidity	1000Hrs.	85℃/85%RH	25pcs	0/1

2) Criteria for Judging the Damage:

Item	Symbol	Test Conditions	Criteria for Judgment		
		lest conditions	Min	Max	
Forward Voltage	VF	IF=20mA		F.V.*)×1.1	
Reverse Current	IR	VR=5V		F.V.*)×2.0	
Luminous Intensity	IV	IF=20mA	F.V.*)×0.7		

*) F.V.: First Value.



Please read the following notes before using the product:

1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package, the LEDs should be kept at 30° C or less and 90%RH or less.

2.3 The LEDs should be used within a year.

2.4 After opening the package, the LEDs should be kept at 30° C or less and 70%RH or less.

2.5 The LEDs should be used within 168 hours (7 days) after opening the package.

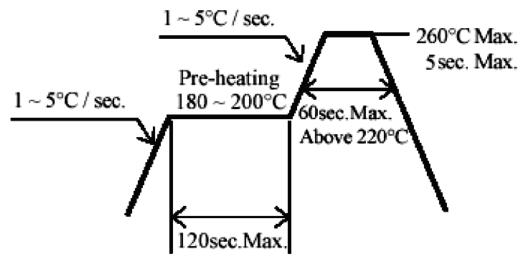
2.6 If the moisture adsorbent material (silica gel) has fabled away or the LEDs have exceeded the storage

time, baking treatment should be performed using the following conditions. Baking treatment: 60±5°C for

24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile.



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

3.4 After soldering, do not warp the circuit board.

4. Soldering Iron

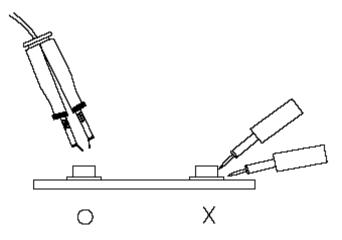
Each terminal is to go to the tip of soldering iron temperature less than 260° C for 5 seconds within once in

less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether

the characteristics of the LEDs will or will not be damaged by repairing.



6. Caution in ESD

Static Electricity and surge damages the LED. It is recommended to use a wrist band or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.